

(a) 1- Spin photoresist on silicon



2- Photolithography



3- Spin and cure PDMS



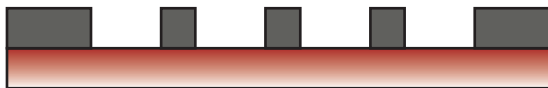
4- Demold



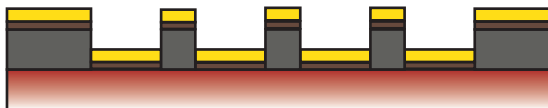
(b) 1- Spin photoresist on glass



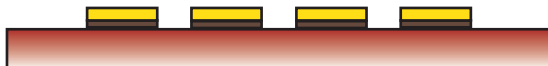
2- Photolithography



3- E-beam deposition



4- Lift-off



(c) Final device assembly

